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PK35 Device Structure

Rev.1.0

PHENITEC SEMICONDUCTOR Corp.

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Contents

- 1. About Layout pattern and Dark/Clear
- 2. Device Cross section

MPM(5V Pch Medium Vt)

MPL(5V Pch Low Vt)

MPL2(5V Pch very Low Vt)

MPN(5V Pch Native Vt)

MPMI(5V Pch Medium Vt Iso)

MPLI(5V Pch Low Vt Iso)

MPL2I(5V Pch very Low Vt Iso)

MPNI(5V Pch Native Vt Iso)

MNM(5V Nch Medium Vt)

MNH(5V Nch High Vt)

MNL(5V Nch Low Vt)

MND(5V Nch Depletion Vt)

MNN(5V Nch Native Vt)

MNE_LC, MNE_PC(5V Nch Esd protection/8finger, 10finger)

MNMI(5V Nch Medium Vt Iso)

MNHI(5V Nch High Vt Iso)

MNLI(5V Nch Low Vt Iso)

MNDI(5V Nch Depletion Vt Iso)

MNNI(5V Nch Native Vt Iso)

MNEI_LC, MNEI_PC(5V Nch Esd protection Iso/8finger, 10finger)

RPL(Low Resistance Poly-Si Resistor [95 Ω /s])

RPM(Medium Resistance Poly-Si Resistor[330 Ω /s])

RPH, RPH2(High Resistance Poly-Si Resistor[$5k\Omega/s$], [$8k\Omega/s$])

RNW(Nwell Diff. Resistor)

RN(N+ Diff. Resistor)

RP(P+ Diff. Resistor)

CPIP(PIP Capacitor)

CND(Nch Depletion Vt Capacitor)

CNDI(Iso Nch Depletion Vt Capacitor)

CPL2(Pch Very Low Vt Capacitor)

CPL2I(Iso Pch Very Low Vt Capacitor)

PNP(Vertical PNP (P+/Nwell/Psub))

PNP2(Vertical PNP (P+/Nwell+DNW/Psub))

NPN(Vertical NPN (N+/Pwell/DNW)

RFS(Poly-Si Laser Trimming Fuse)

DP(P+/Nwell Diode)

DP2(P+/Nwell in Niso Diode)

DN(N+/Pwell Diode)

DN2(N+/Pwell in Niso Diode)

P (3.3V Pch MOS)

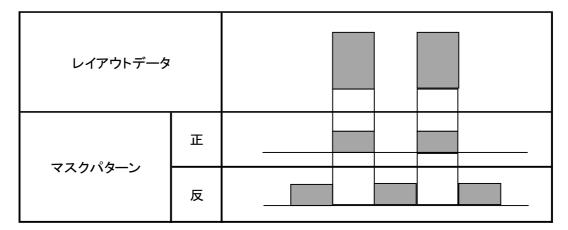
N (3.3V Nch MOS)

- 3. Fuse Opening-part Cross section
- 4. Relation between Mask and Implant for CRP (1st Poly-Si)
- 5. Revision History

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1. About Layout pattern and Dark/Clear

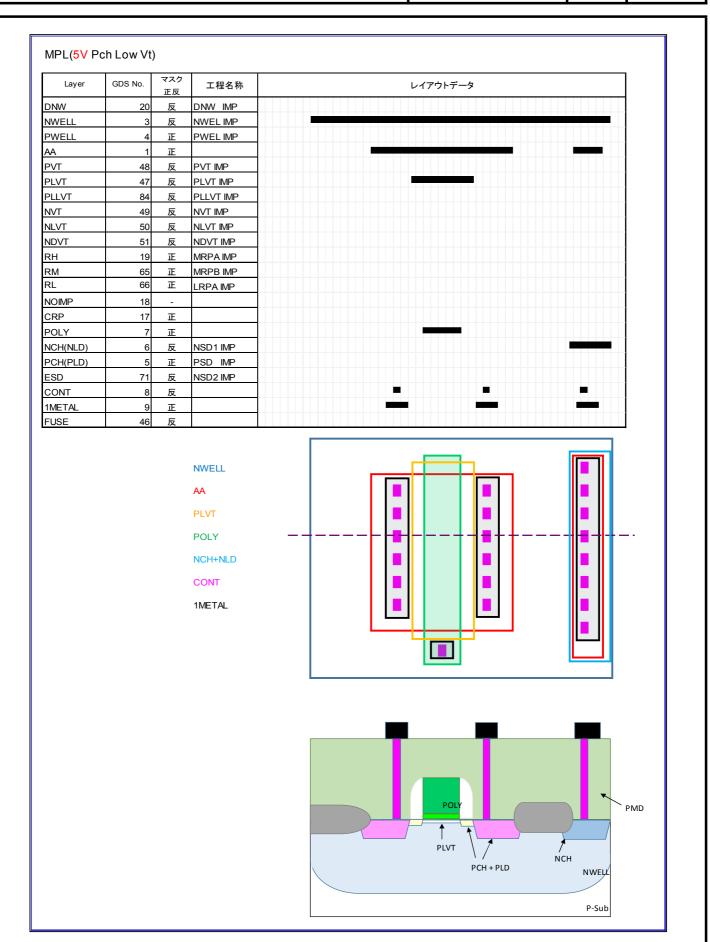
下記にレイアウトデータとマスクの概念を示します。



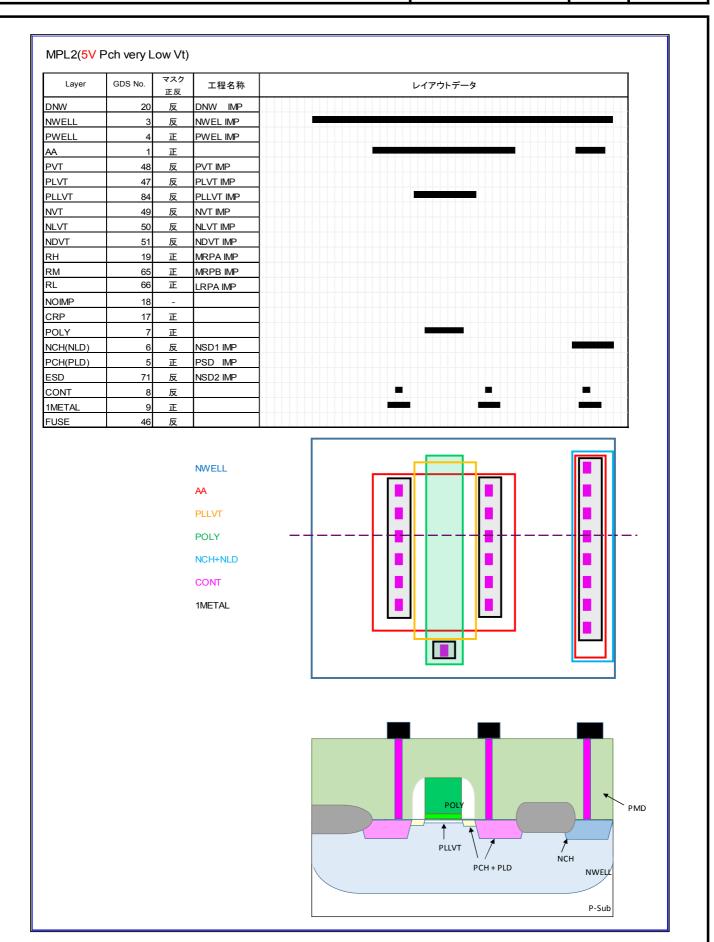
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2. Device Cross section MPM(5V Pch Medium Vt) マスク GDS No. Layer 工程名称 レイアウトデータ DNW DNW IMP 反 NWELL 反 NWEL IMP PWELL PWEL IMP PVT 反 PVT IMP PLVT 反 PLVT IMP PLLVT 反 PLLVT IMP NVT 反 NVT IMP NLVT 50 反 NLVT IMP NDVT 51 NDVT IMP 反 MRPA IMP RH RM 65 MRPB IMP 66 RL LRPA IMP NOIMP 18 CRP 正 POLY 正 NCH(NLD) 6 反 NSD1 IMP PCH(PLD) PSD IMP 正 ESD 71 NSD2 IMP 反 CONT 8 反 1METAL 9 正 46 FUSE NWELL AAPVT POLY NCH+NLD CONT 1METAL PMD PVT NCH PCH + PLD NWELL

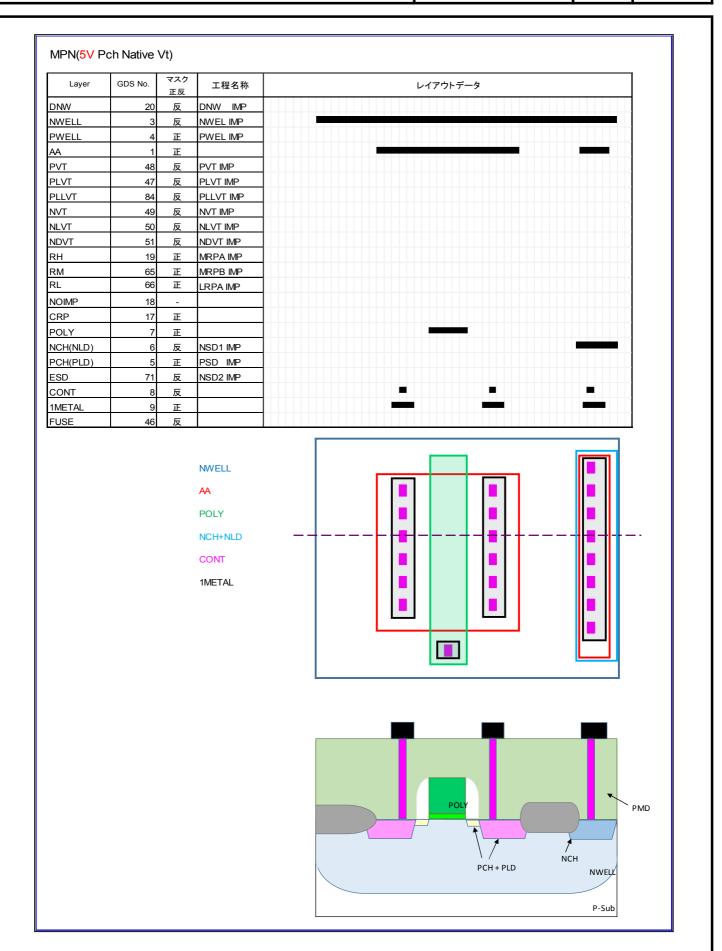
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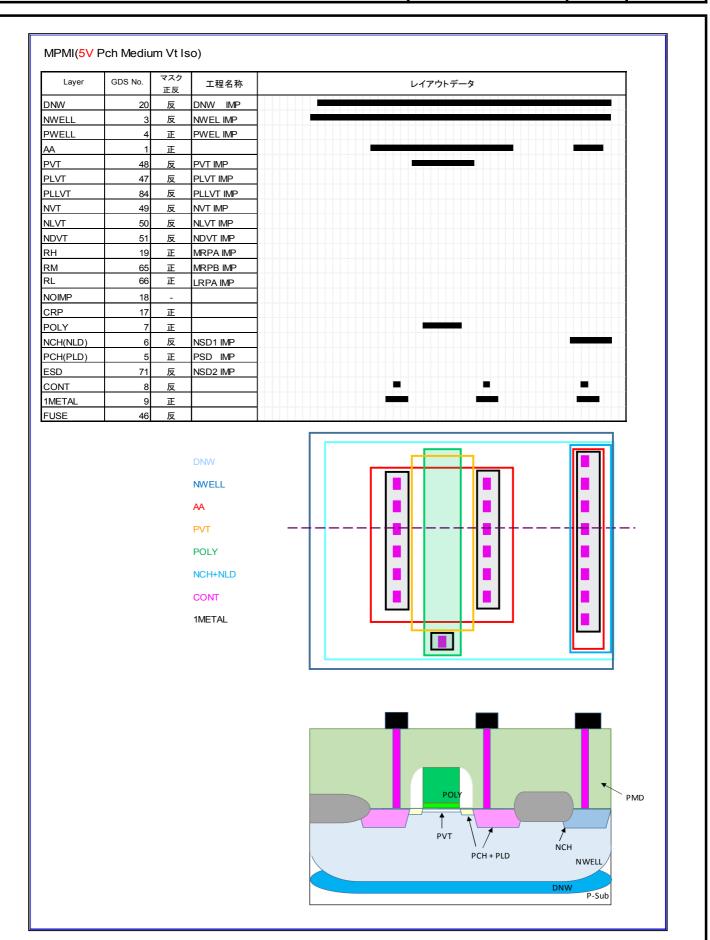
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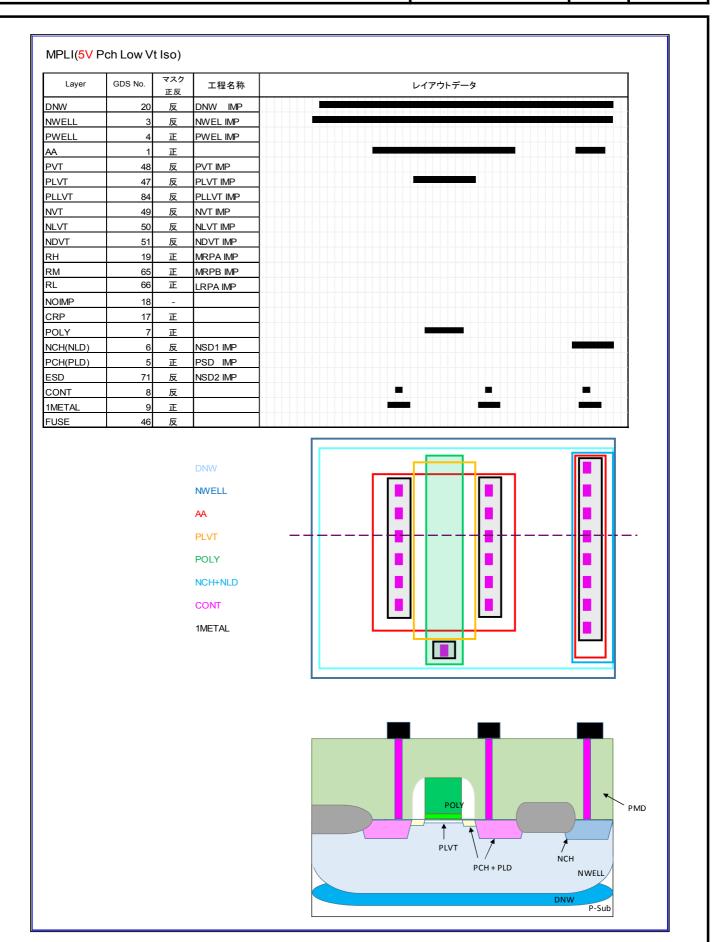
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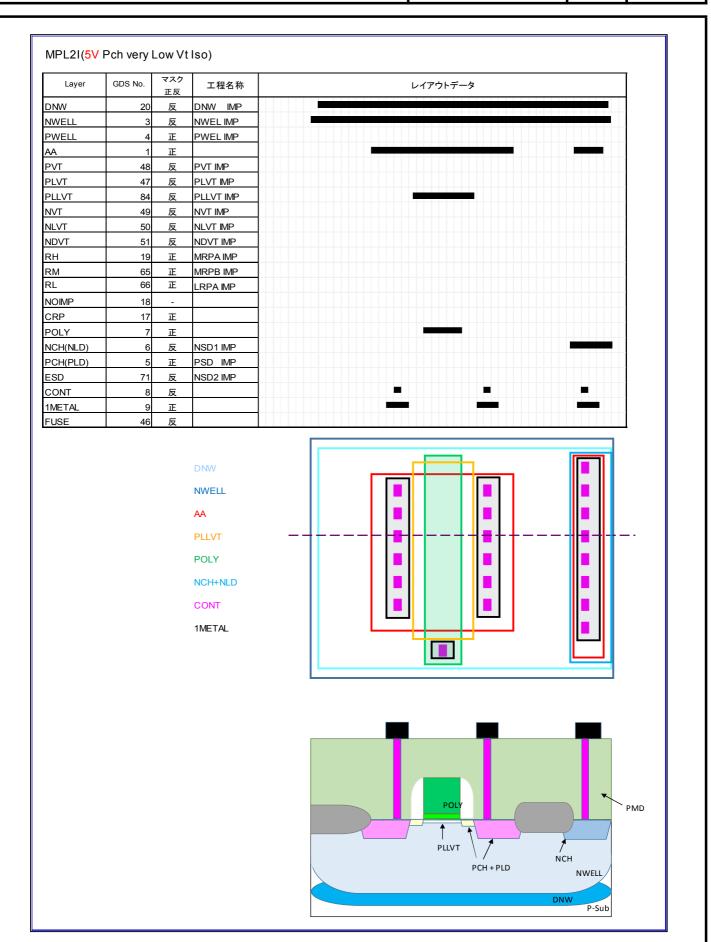
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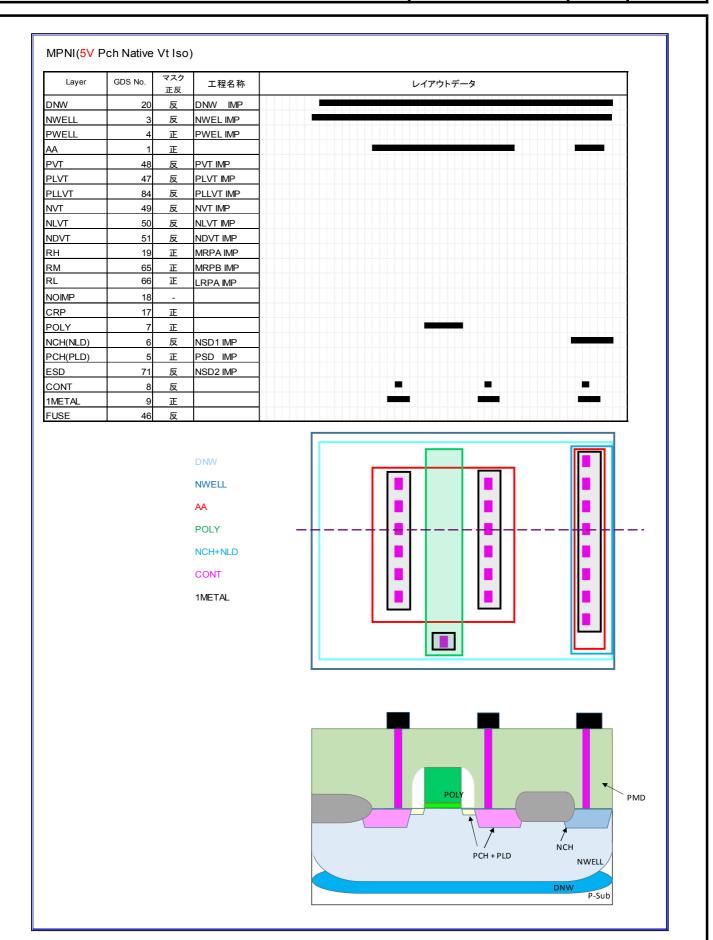
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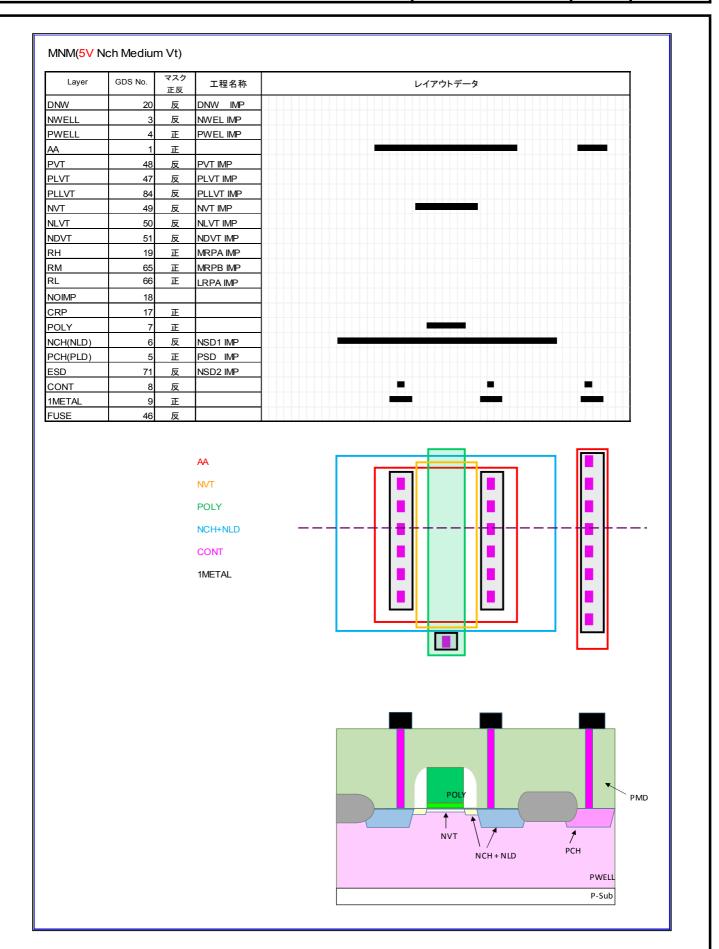
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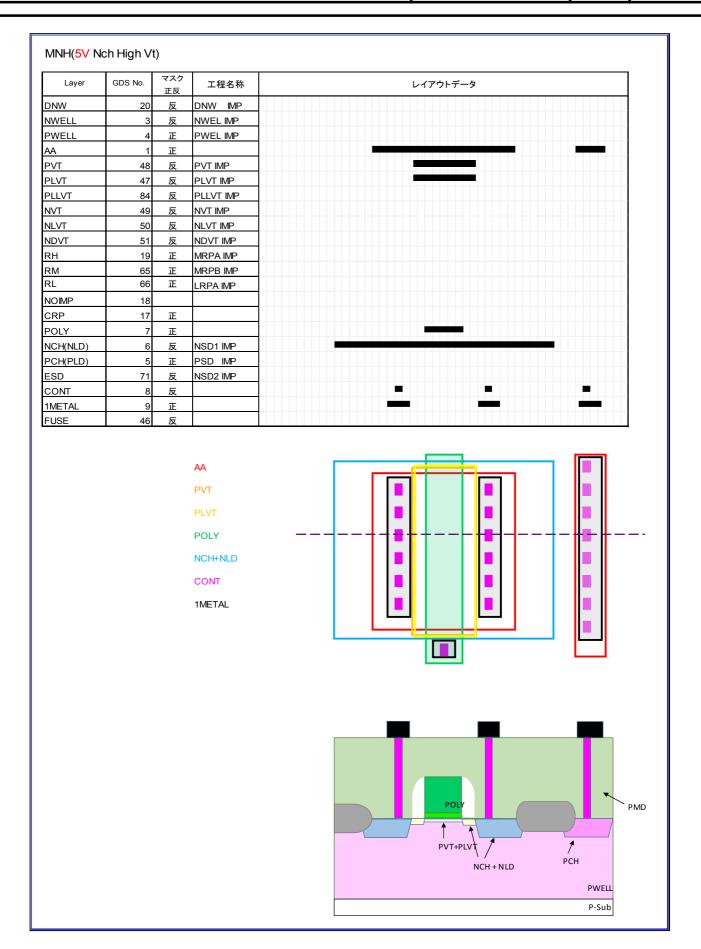
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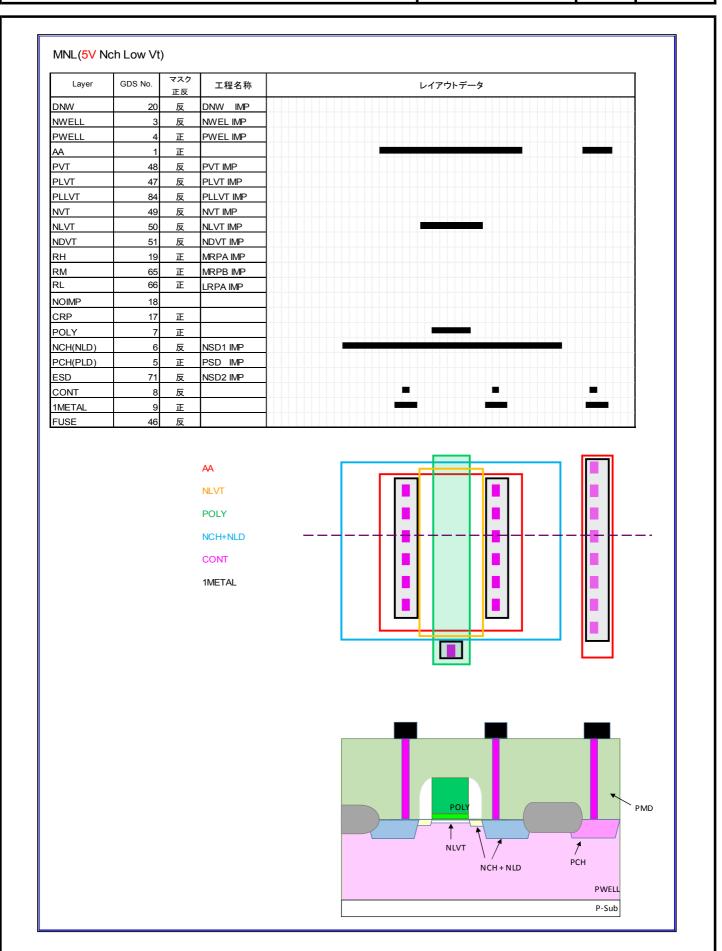
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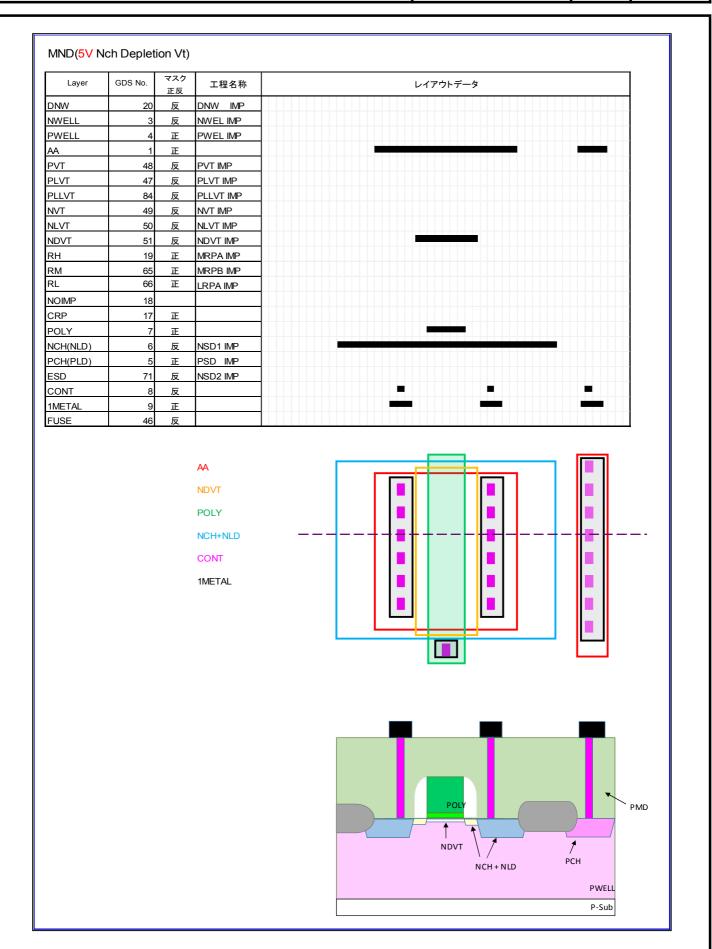
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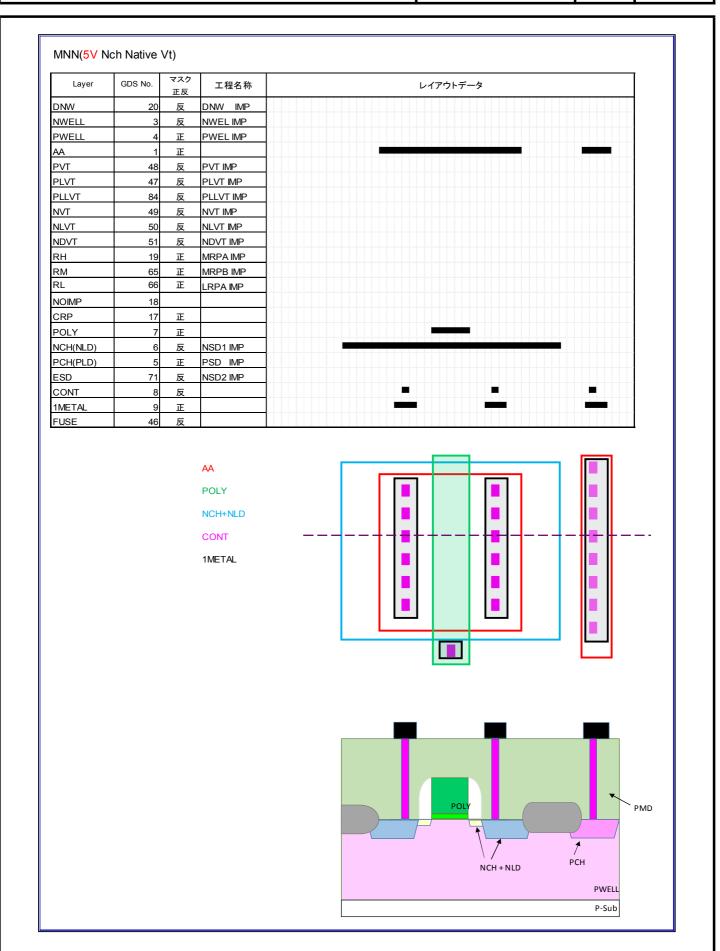
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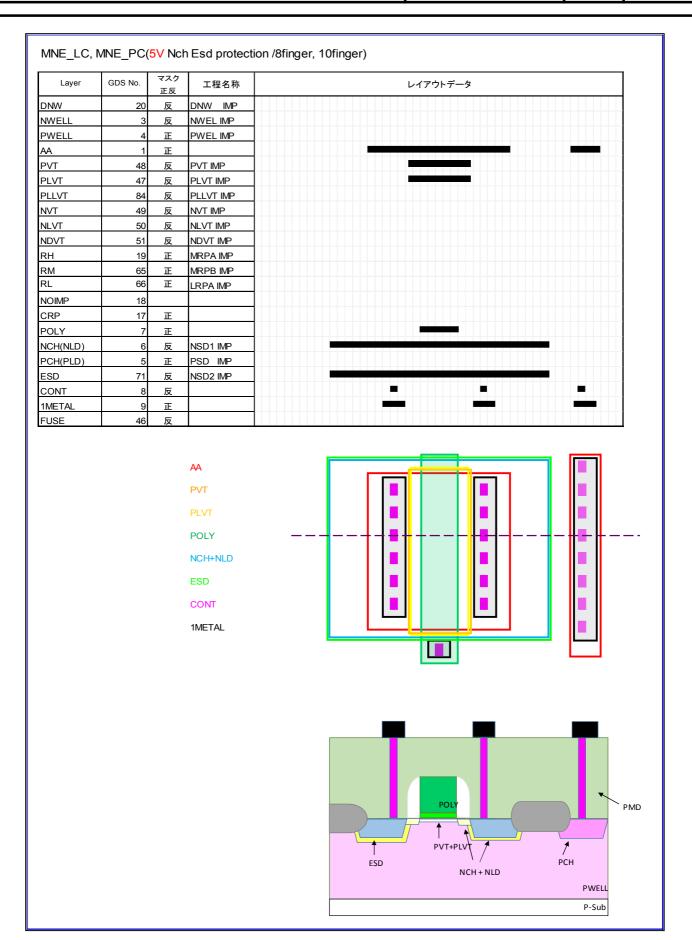
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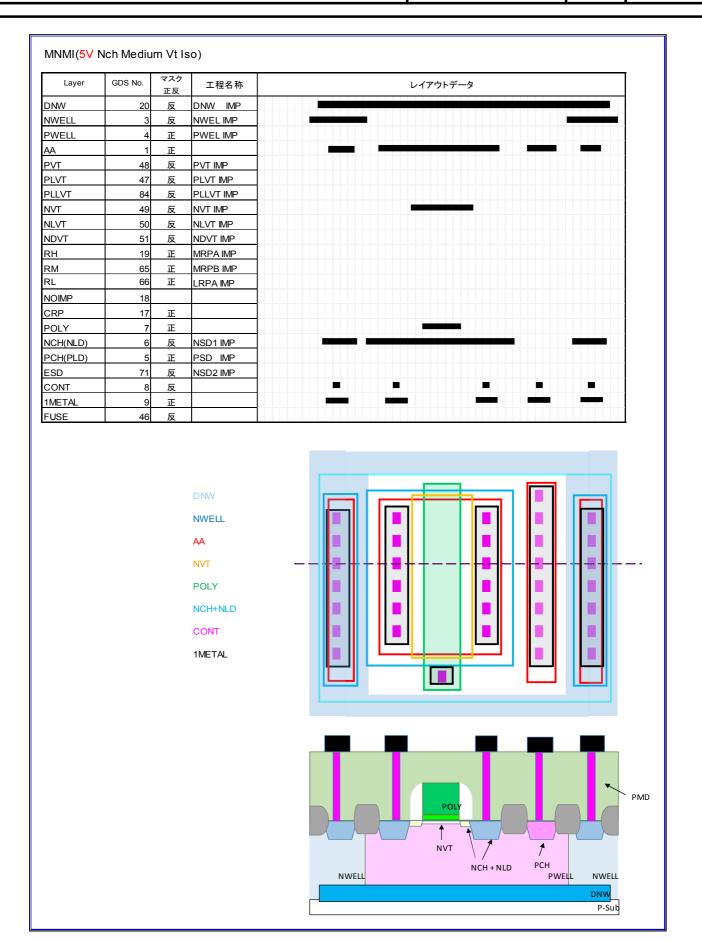
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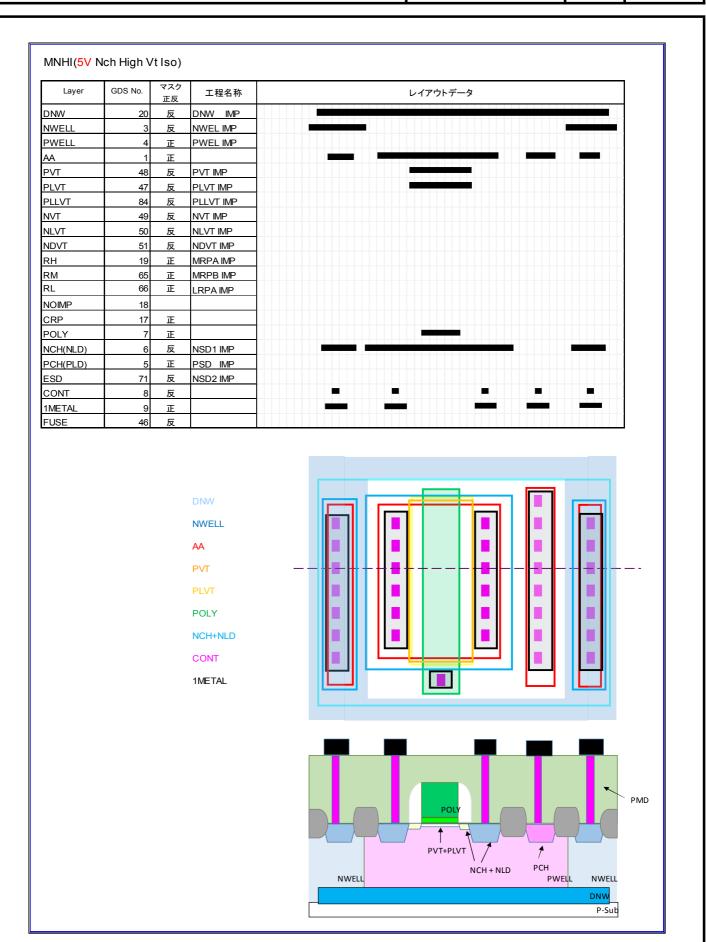
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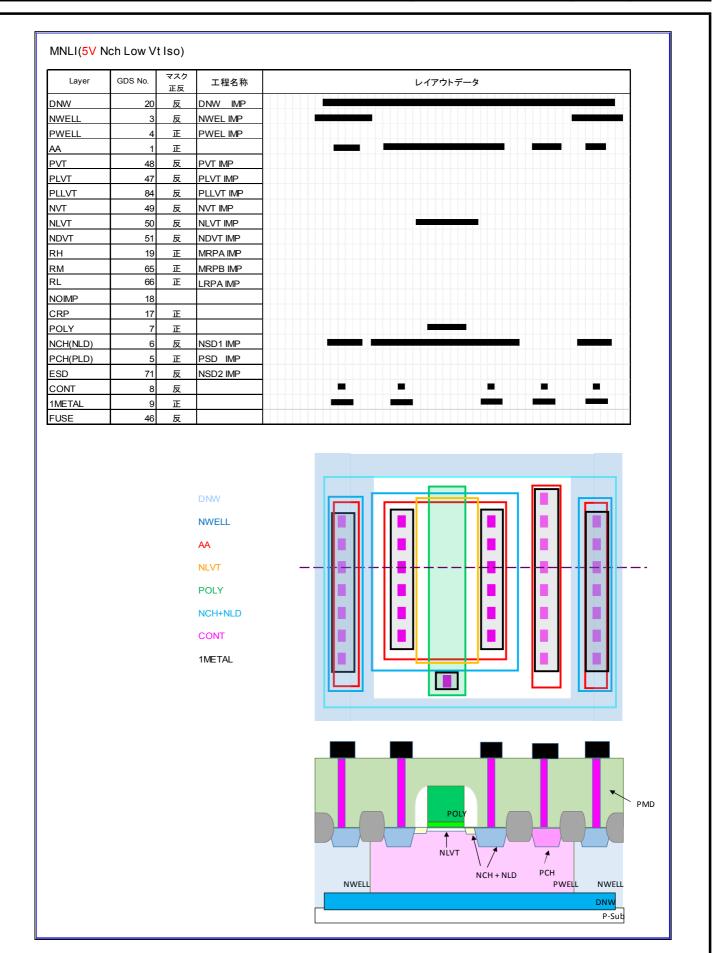
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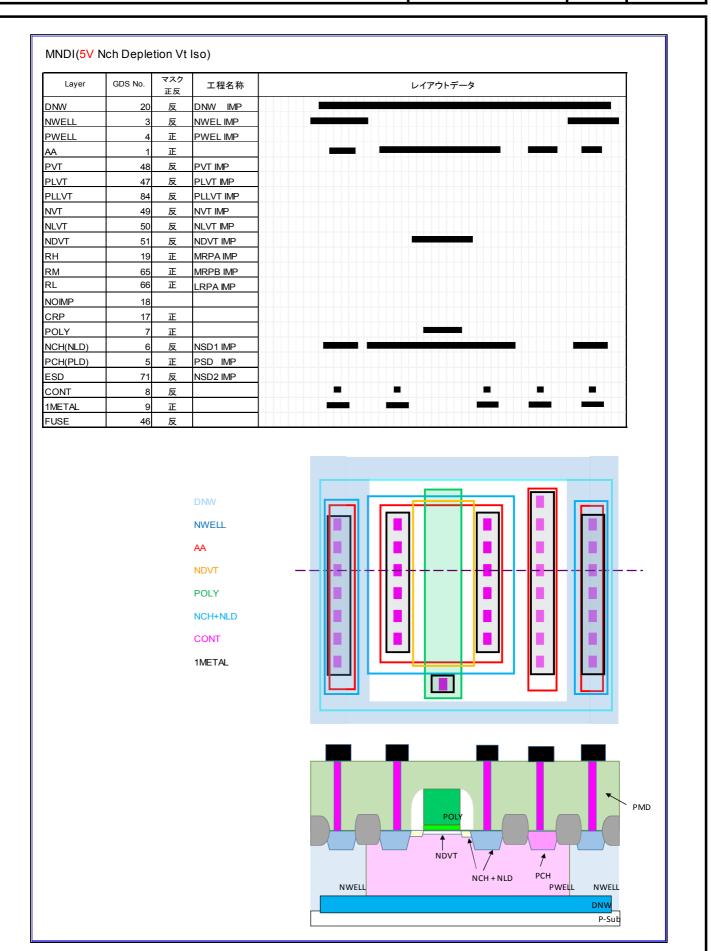
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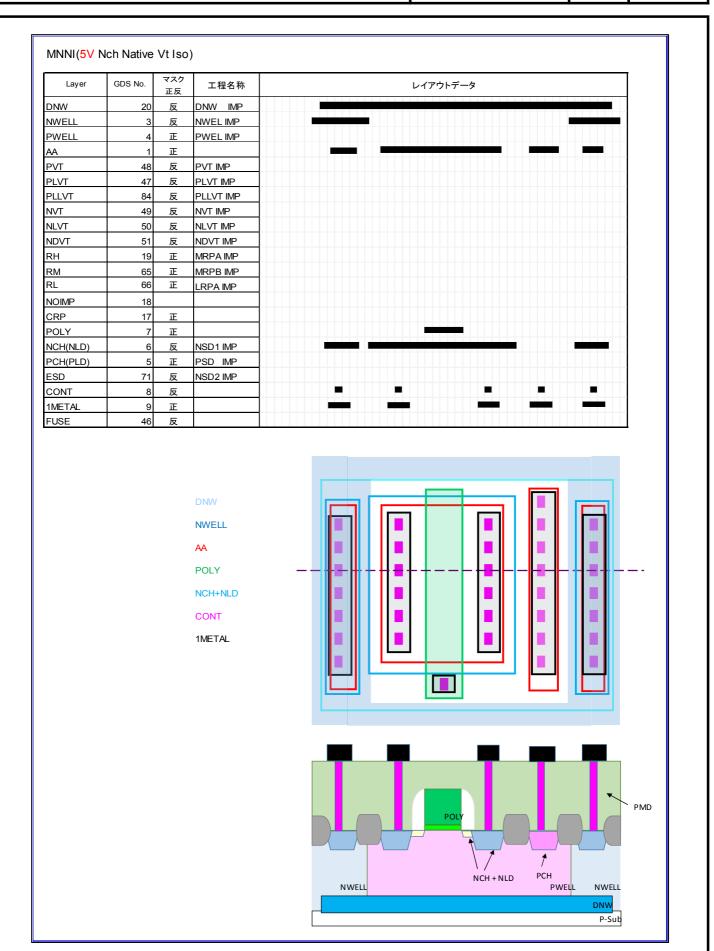
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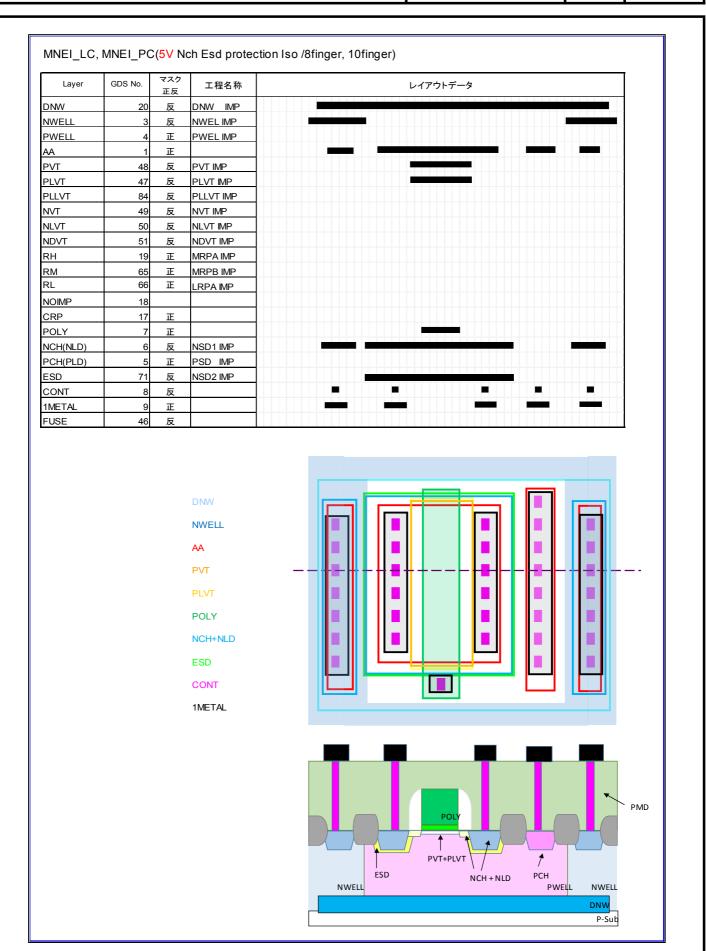
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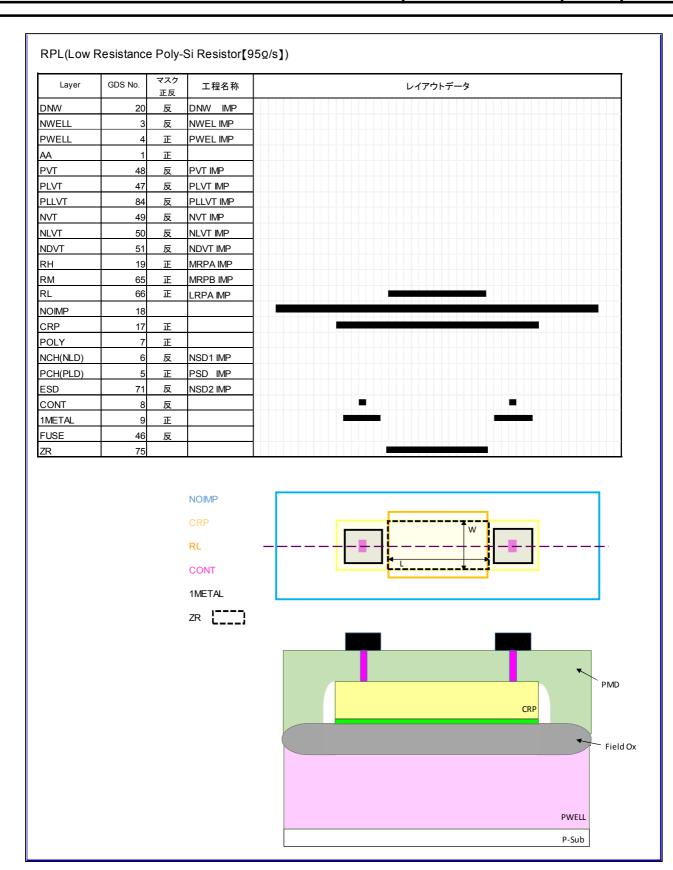
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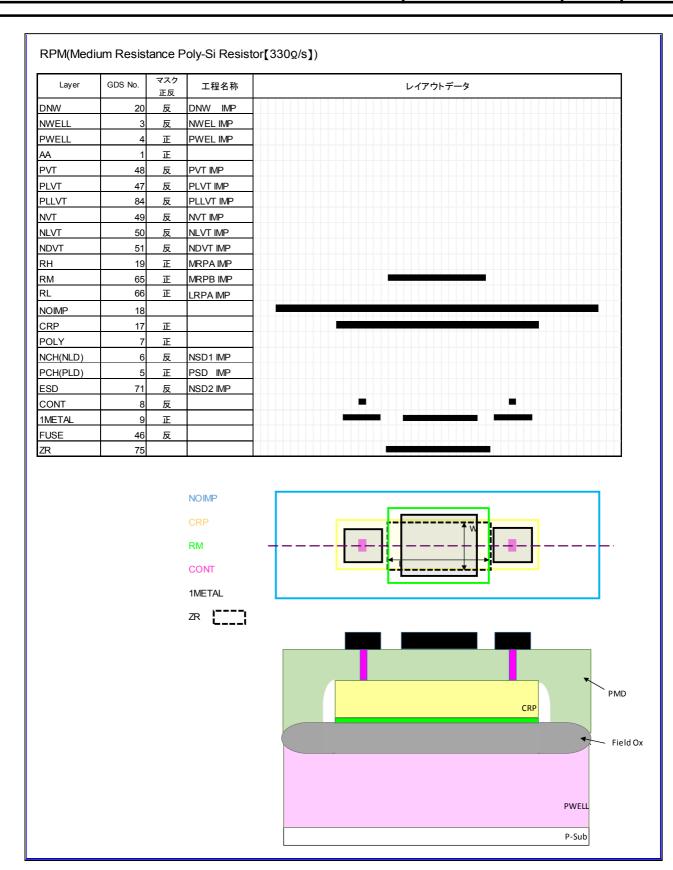
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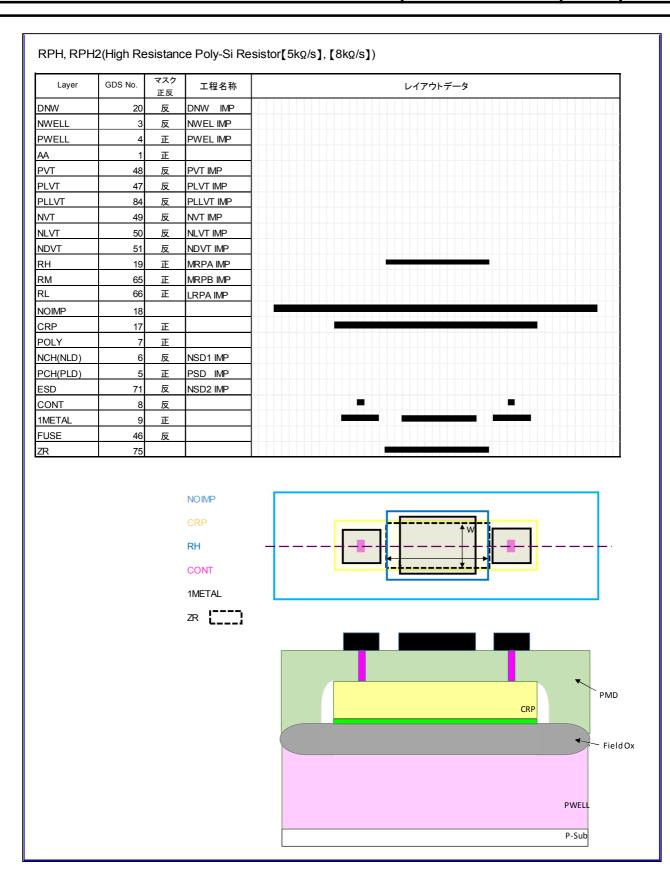
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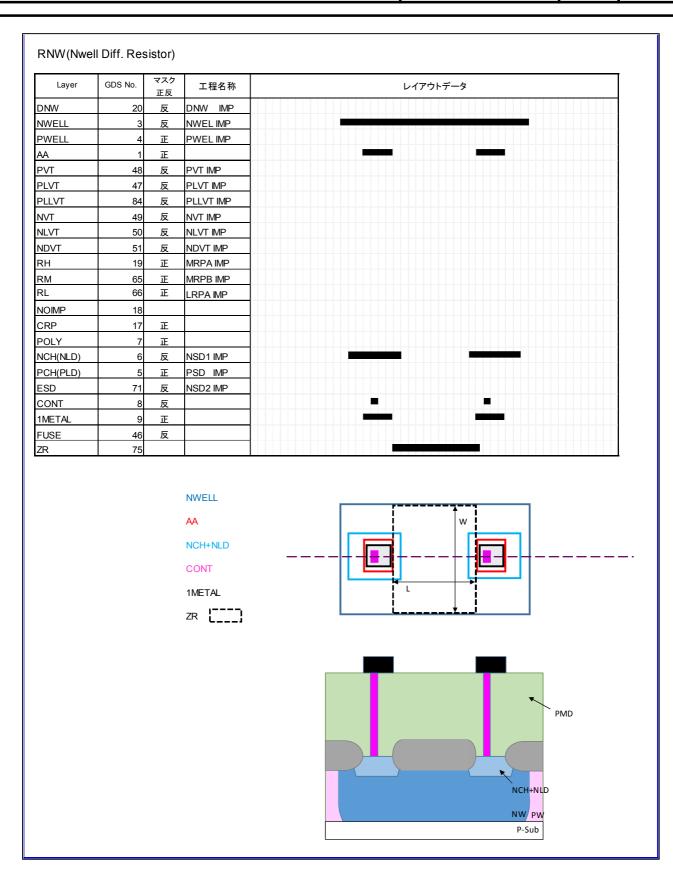
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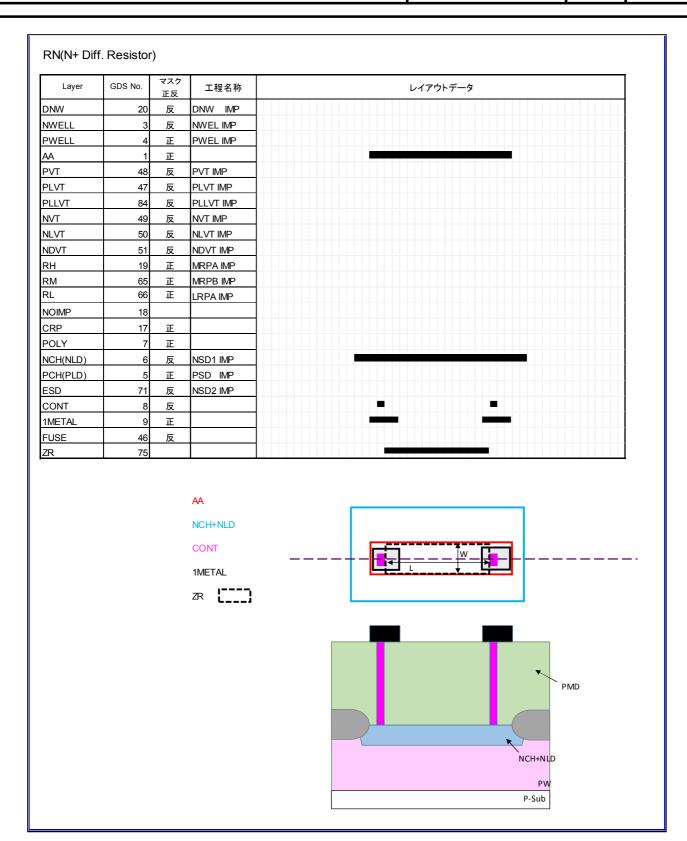
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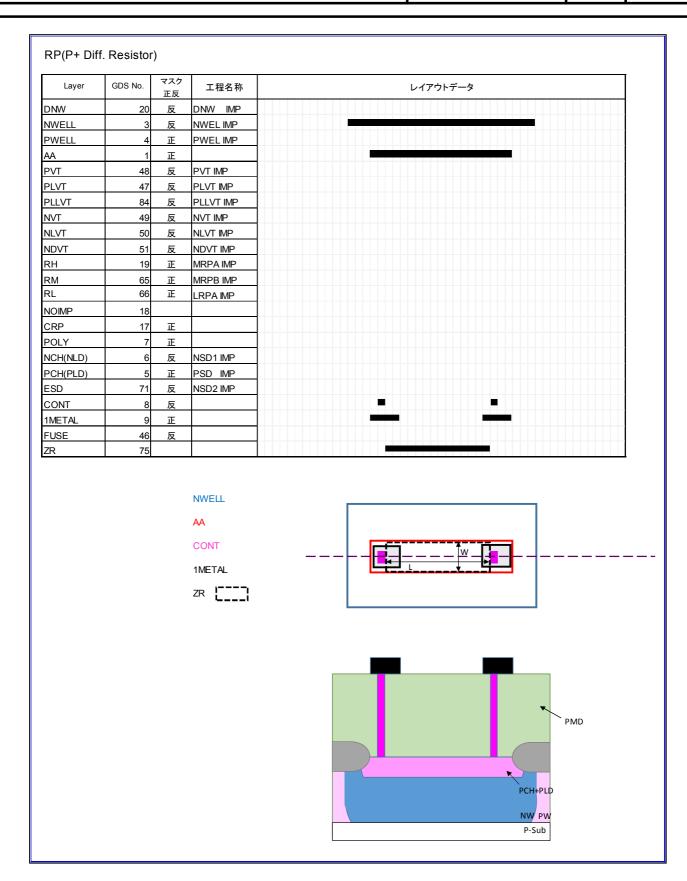
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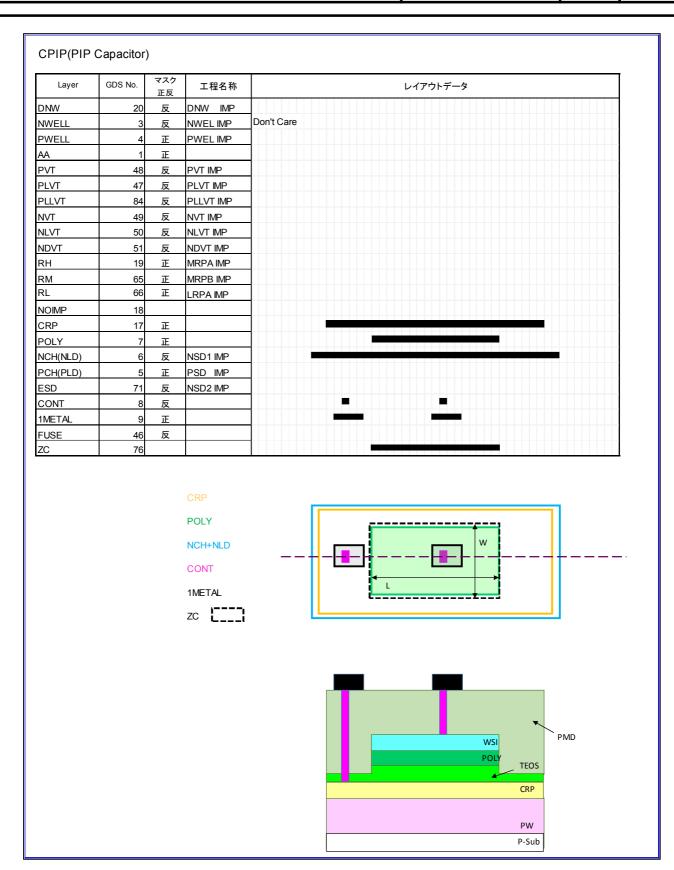
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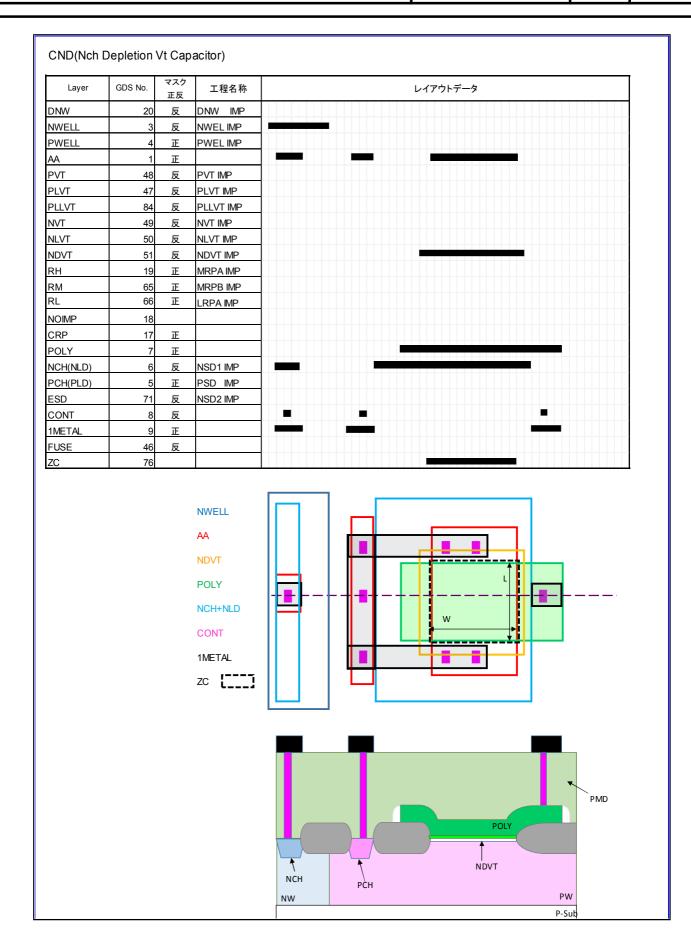
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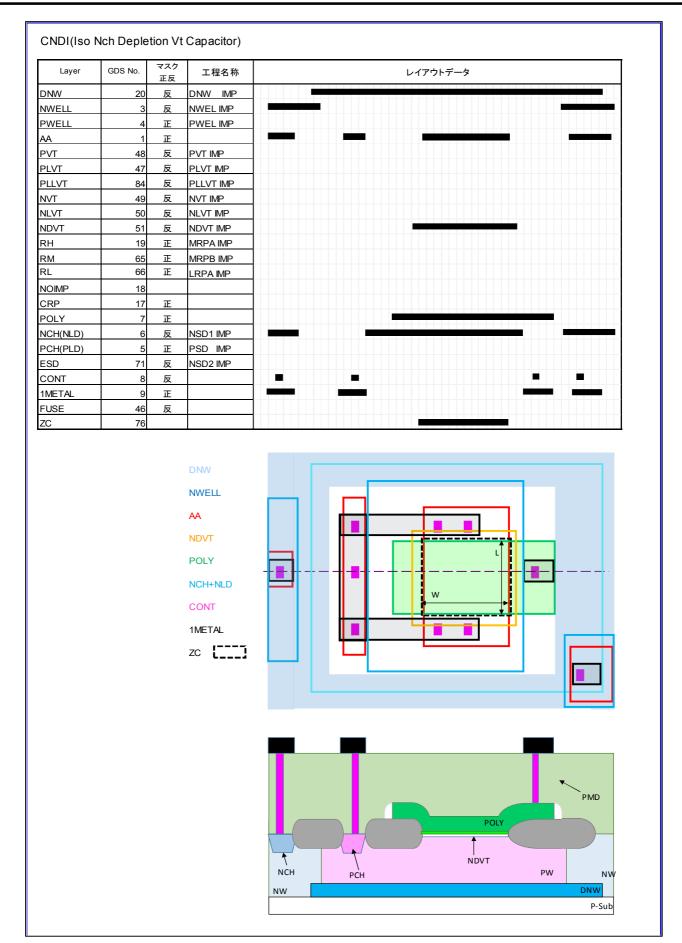
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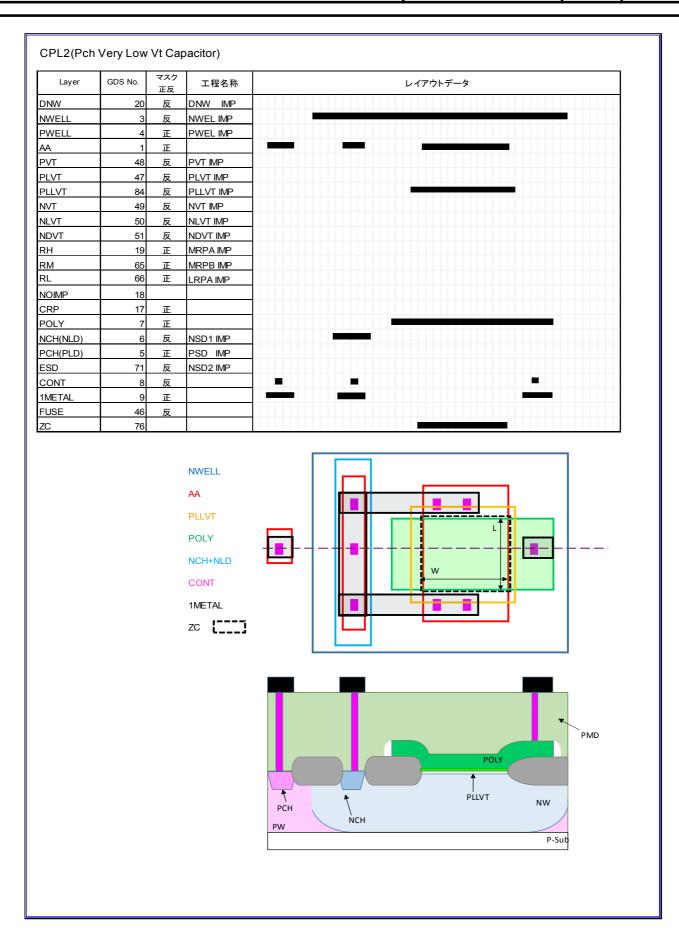
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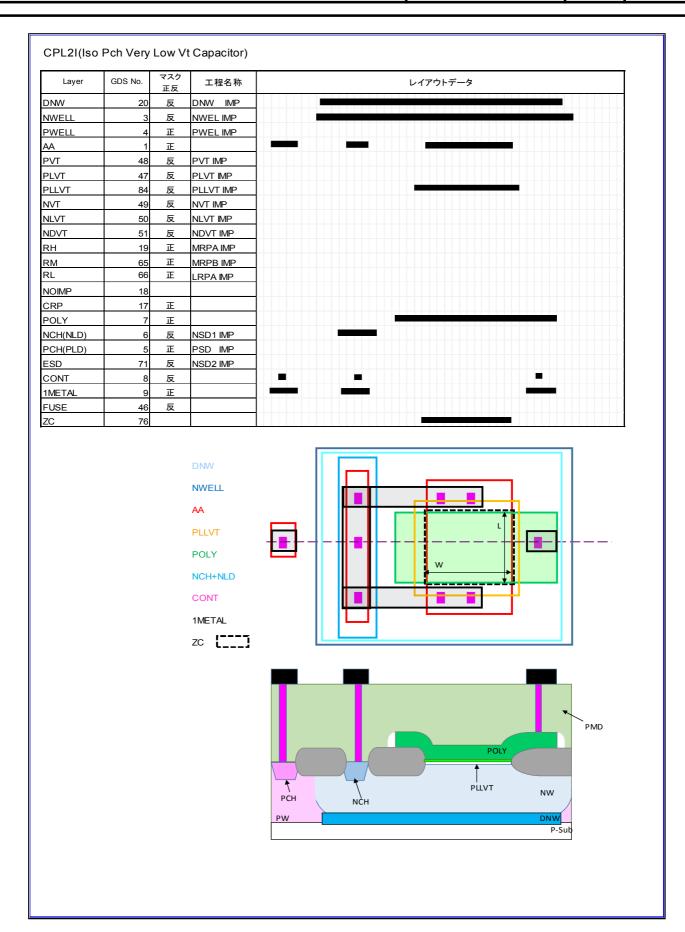
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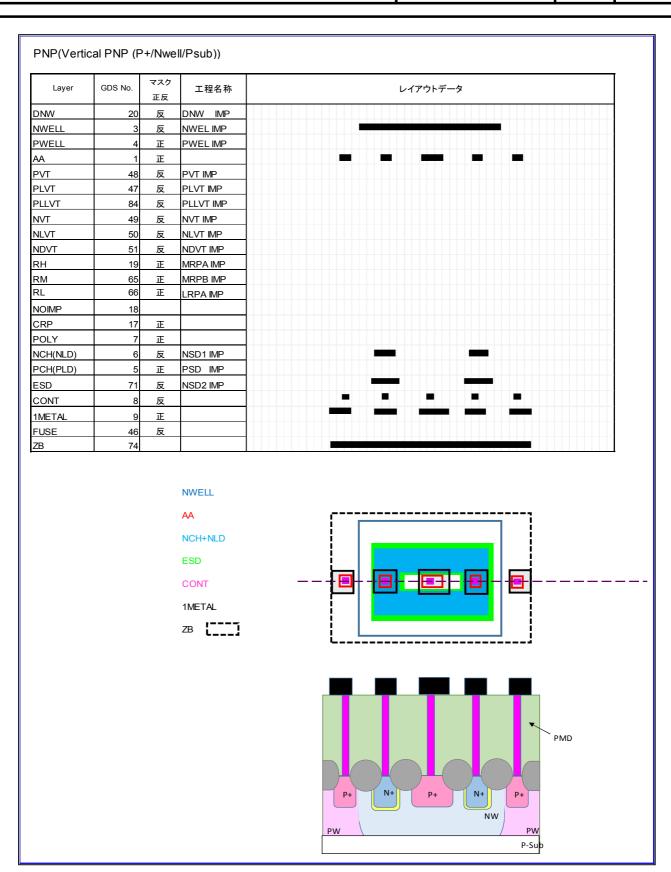
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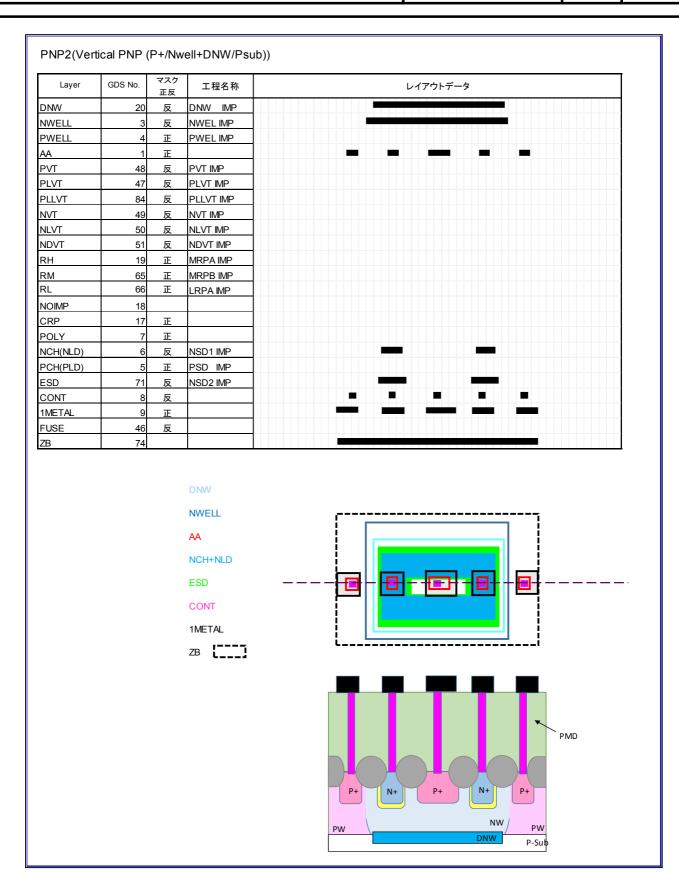
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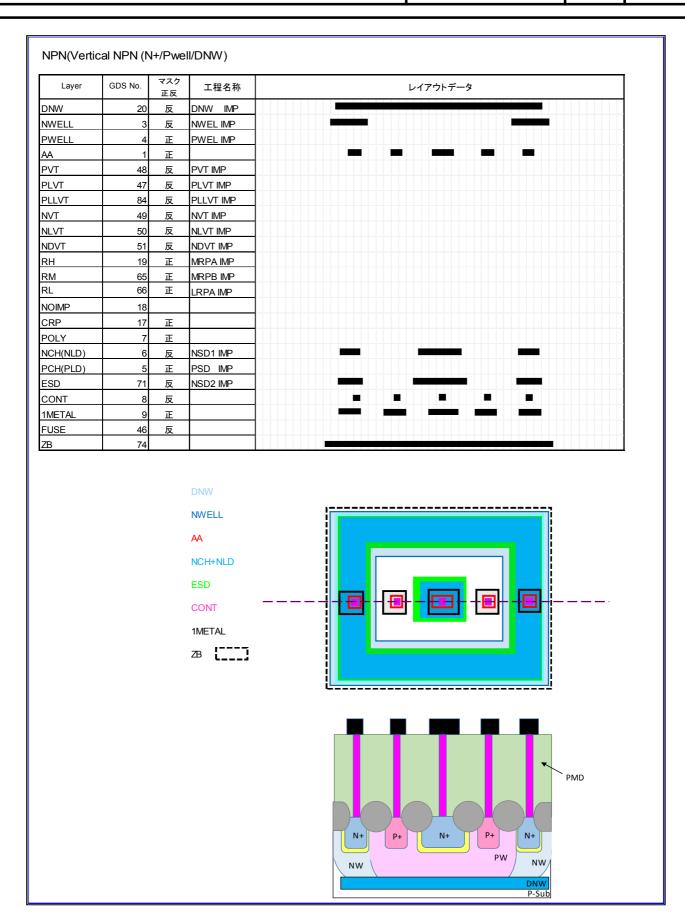
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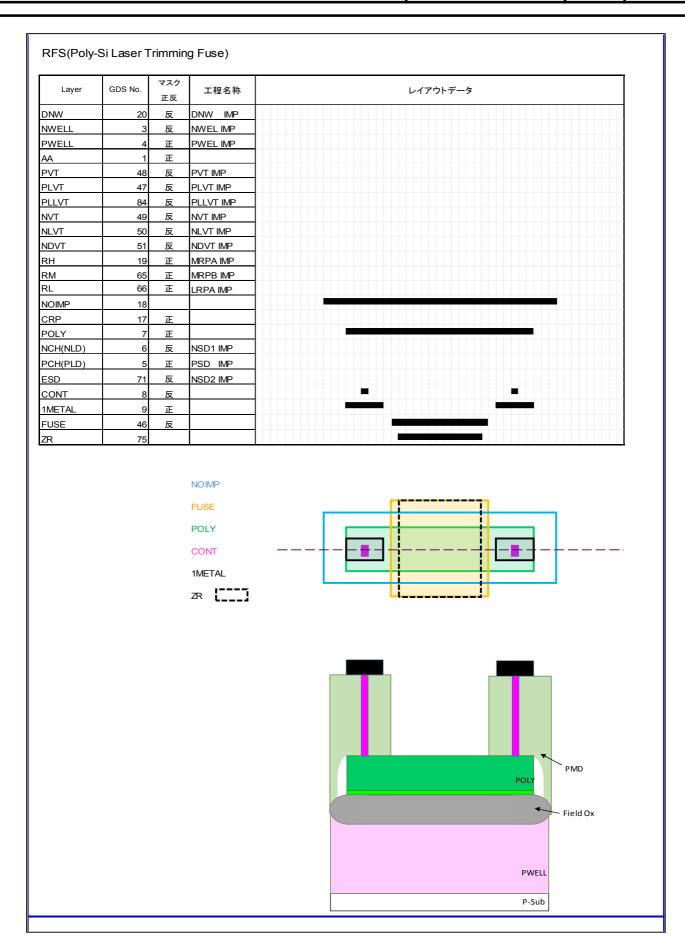
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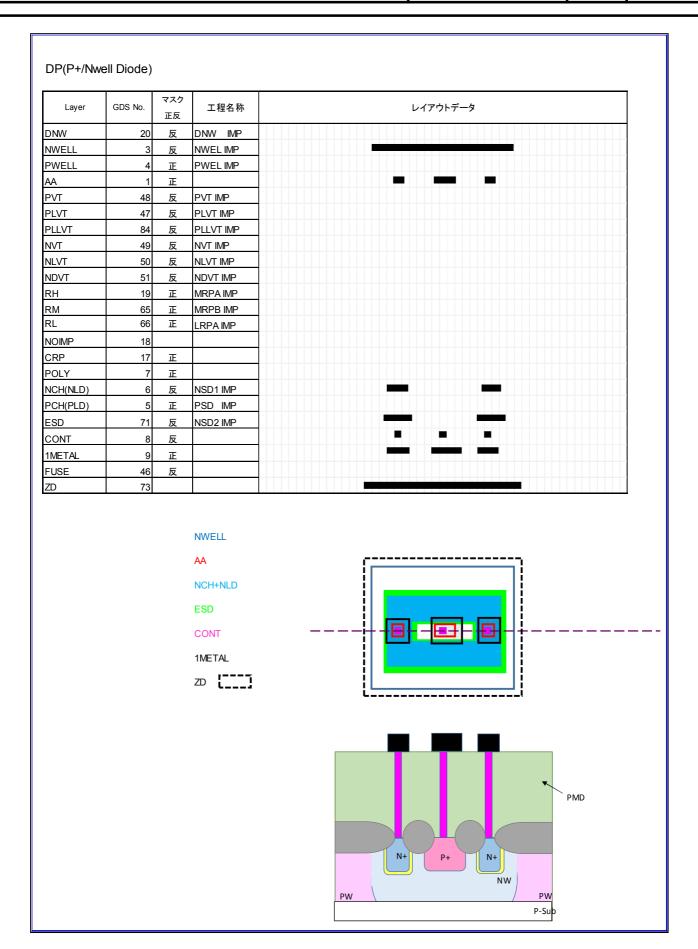
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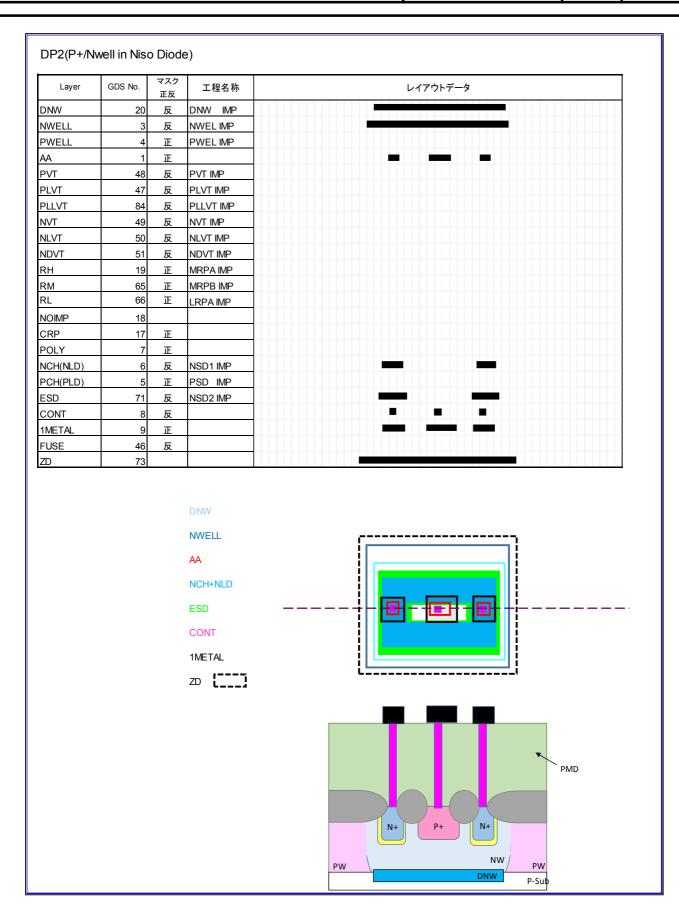
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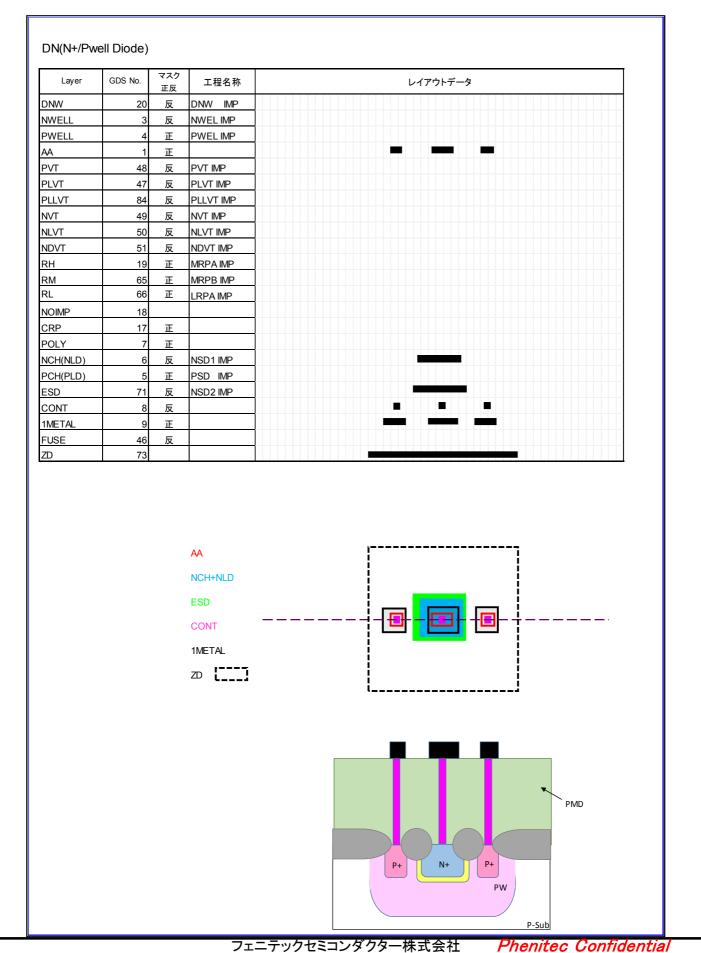
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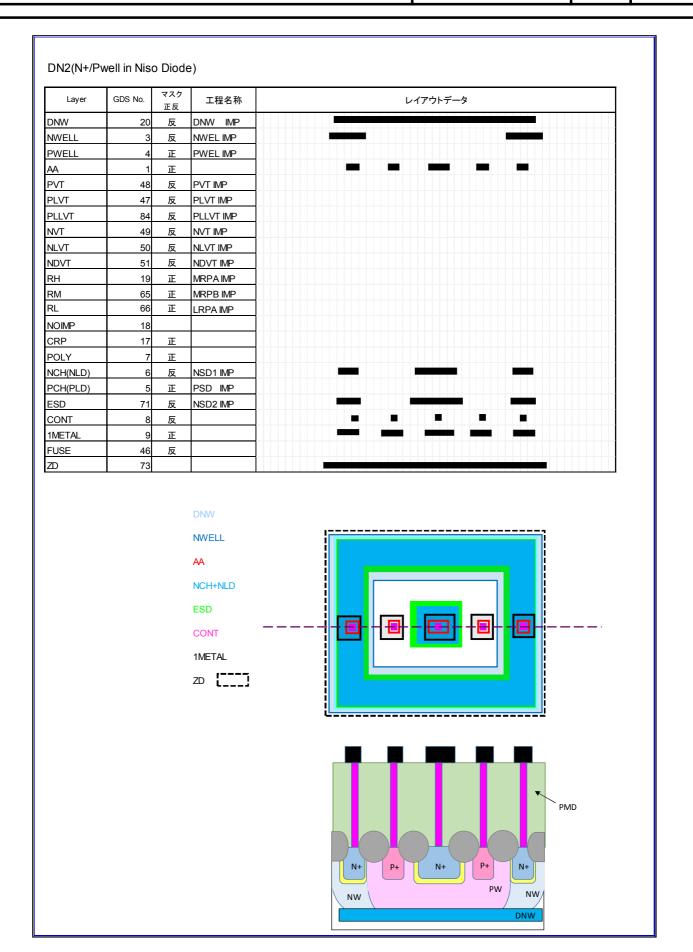
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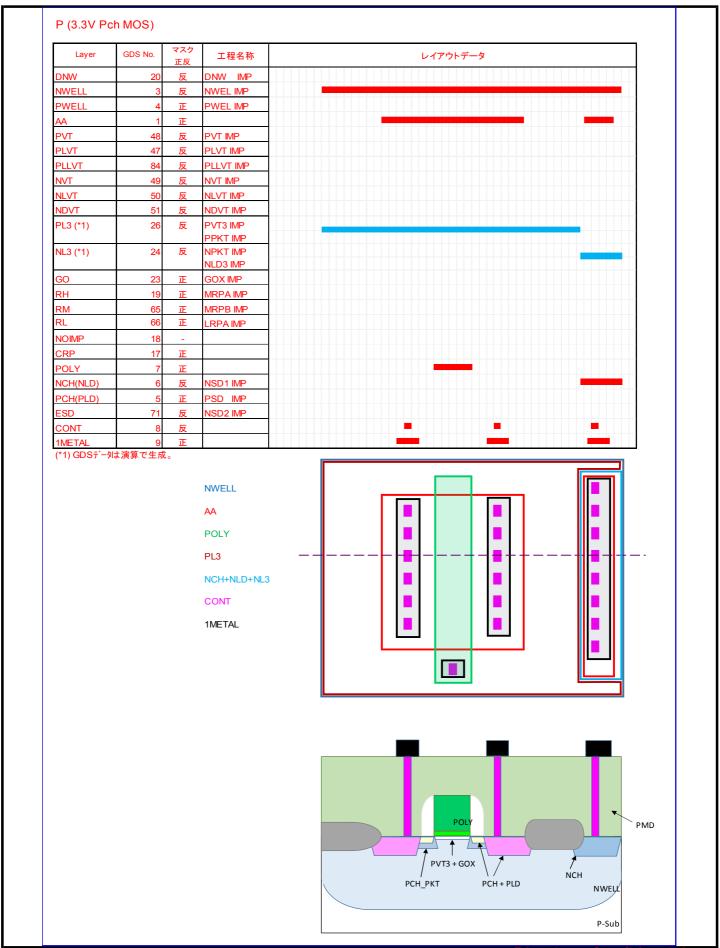
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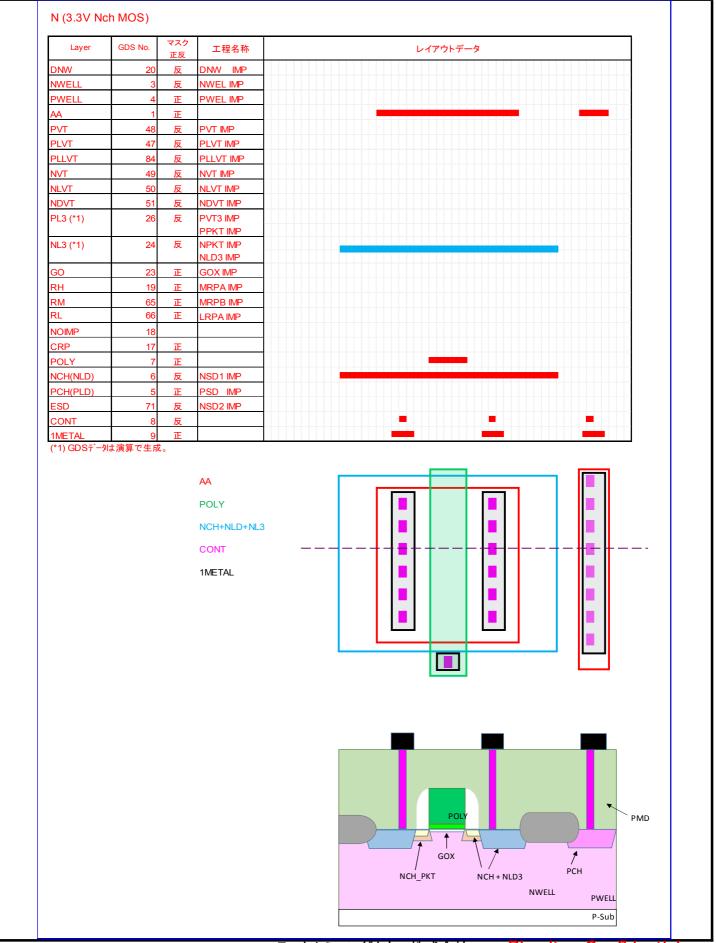
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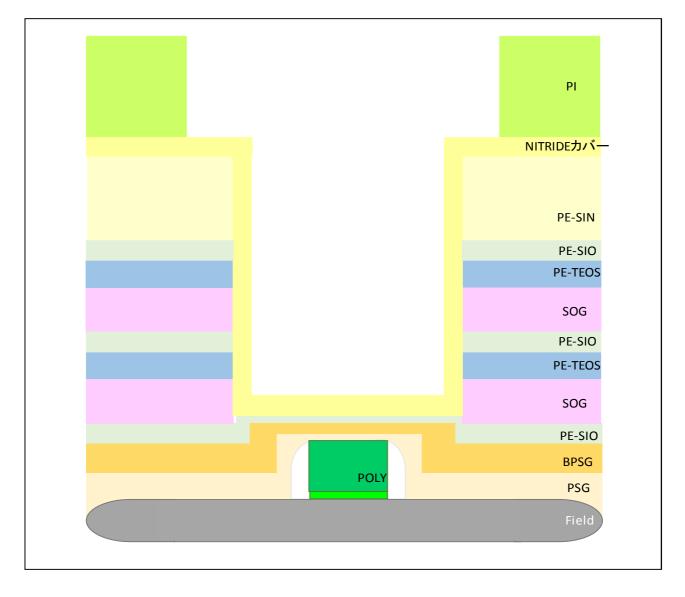


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3. Fuse Opening-part Cross section



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4. Relation between Mask and Implant for CRP (1st Poly-Si) [Matrix of Mask and Implant for each device area] Mask Poly-Si Resistor Layer PIP Capacitor Gate-Poly Process Name Body area Dark/ Composition Bottom plate (1st Poly-Si) Tap area Clear **RPL** RPH/RPH2 **RPM** HR Impla (Blanket Implant) MRPA Mask RH Dark chrome MRPA Impla ✓ ✓ MRPB Mask RH+RM Dark chrome chrome MRPB Impla √ RH+RM+RL LRPA Mask Dark chrome chrome chrome LRPA Impla X √ X ✓ 1 Impurity Concentration \rightarrow Lower ← Higher Higher ← Lower Poly Sheet Resistance \rightarrow *Notation Implanted chrome on Mask N/A No chrome on Mask Not Implanted [Cross sectional diagrams for CRP used device] <RPH, RPH2> $CRP \rightarrow$ Tap Tap Body <MOS-Tr> WSi HR Impla $CRP \rightarrow$ Gate-Poly(1st Poly-Si) <RPM> $\mathsf{CRP} \to$ Tap Body PW or NW Tap HR + MRPA Impla <PIP Capacitor> WSi <RPL> Upper plate(2nd Poly-Si) $CRP \rightarrow$ $CRP \rightarrow$ Bottom plate(1st Poly-Si) Body Tap HR + MRPA + MRPB Impla HR + MRPA + MRPB + LRPA Impla

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Approval	Check	Issue
技術グループ	PDK7 [*] ロジ [*] ェクト	PDK pj
2017/07/26	17.07.26	29/07/26
栗原	大川	喜多川

保管先 技術グループ PDKプロジェクト

4. Revision History

Rev.	Date	Description of change	Issue Check Approval
0.0	2016/11/30	·Initial Release	Akano
0.1	2017/5/16	·Layer_matrix delete	Mituzono
0.2	2017/7/26	Change Device description as following (whole pages) MOS-Tr, MOS-Cap; add "Vt" BJT ·Vertical PNP (P+/Nwell+NIsoPsub) -> (P+/Nwell+DNW/Psub) ·Vertical NPN (N+/Pwell/NIso) -> (N+/Pwell/DNW) Poly Resistor ·Low sheet Poly Resistor -> Low Resistance Poly-Si Resistor[95Ω/s] ·Medium sheet Poly Resistor -> Medium Resistance Poly-Si Resistor[330Ω/s] ·High sheet Poly Resistor[5kohm/sq] -> High Resistance Poly-Si Resistor[5kΩ/s] ·High sheet Poly Resistor[8kohm/sq] -> High Resistance Poly-Si Resistor[8kΩ/s] Laser Poly Fuse ·Fuse -> Poly-Si Laser Trimming Fuse MNE_LC, MNE_PC -> add "/8finger, 10finger" MNEI_LC, MNEI_PC -> add "/8finger, 10finger" Layer table ·change order of layer PVT, RL, NOIMP, FUSE ·add layer ZB for PNP, PNP2, NPN ·add layer ZR for RFS ·delete layer PMP, PPP RPM, RPH, RPH2 ·add 1METAL cover P.3 add Chapter name "2.Device Cross section" P.38 add Chapter name "3.Fuse Opening-part Cross section"	Kitagawa Ohkawa Kurihara)

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4. Revision History

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0.3	2017/08/17	All pages 4.Rev.his.(2)	Change format of header name → Document name control number → Document number ver → Rev. Page addition. (total pages 39 → 40)	Ohkawa PDK7 [*] ェグ*ェクト 17. 08. 17 大川 Kitagawa PDK pj 29/08/17 喜多川 Kurihara 技術グループ
				栗原
0.4	2017/12/07	•change 4. Revision p.39, Relation bet •Add "sheet" Impl	d cross sectional diagrams for CRP used devi	PDK pj 29/12/07 喜多川

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4. Revision History

Rev.	Date	Description of change	Issue Check Approval
0.5	2018/02/16	MOS (excluding native Vt MOS) and all MOS_Capacitor. Illustration correction. (VIMP enclosure of "AA" \rightarrow "gate") 4.Rev.his.(3) Page addition. (total pages $41 \rightarrow 42$)	Ohkawa Kitagawa Kurihara
0.6	2018/03/16	cover(P.0) Total Page 42 → 46 contents(P.1) add DP, DP2, DN, DN2 DP(P+/Nwell Diode) (P.38) sheet addition DP2(P+/Nwell in Niso Diode) (P.39) sheet addition DN(N+/Pwell Diode) (P.40) sheet addition DN2(N+/Pwell in Niso Diode) (P.41) sheet addition Change "工程名称": I2 -> IMP	Mitsuzono PDK pj 2018/03/22 満園 Kitagawa PDK pj 2018/3/23 喜多川 Kurihara 技術グループ 2018/03/23 栗原
1.0	2019/09/06	■Upgraded Rev.0.6 to Rev.1.0 by adding 3.3V_MOS. cover(P.0) Total Page 46 → 48 contents(P.1) add "5V" to description of all 5V_MOS. add 3V_MOS (P, N). P.3 ~ P.22 add "5V" to description of all 5V_MOS. P (3.3V Pch MOS) (P.42) sheet addition N (3.3V Nch MOS) (P.43) sheet addition	Ohkawa 技術1課 19. 08. 22 大川 Kitagawa 技術1課 2019/8/26 喜多川 Takenaka 技術1課 2019/09/06 竹中 Kurihara